United States Patent [19]

Kudoh et al.

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[45] **Date of Patent: ** Oct. 25, 1988**

[54] **LEAD FRAME FOR A SEMICONDUCTOR ELEMENT OR THE LIKE**

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[73] Assignee: **Sumitomo Electric Industries, Ltd.,** Osaka, Japan

[**] Term: **14 Years**

[21] Appl. No.: **726,737**

[22] Filed: **Apr. 24, 1985**

[52] **U.S. Cl.** **D13/99;** D13/24

[58] **Field of Search** .... D13/11-13, D13/20, 23-31, 99; 339/17 CF, 176 M, 17 R, 17 L, 176 MP; 361/421; 174/52 FP; 357/70

[56] **References Cited**

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Conference: Eleventh Annual Connector Symposium Proceedings, Cherry Hill, N.J., 10/25/78, FIG. 1 on p. 2.

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[57] **CLAIM**

The ornamental design for a lead frame for a semiconductor element or the like, as shown and described.

DESCRIPTION

FIG. 1 is a top plan view of a lead frame for a semiconductor element or the like showing our new design, the bottom being a mirror image thereof;

FIG. 2 is a right side elevational view thereof, the opposite side being a mirror image thereof; and

FIG. 3 is a front elevational view thereof, the rear being a mirror image thereof.

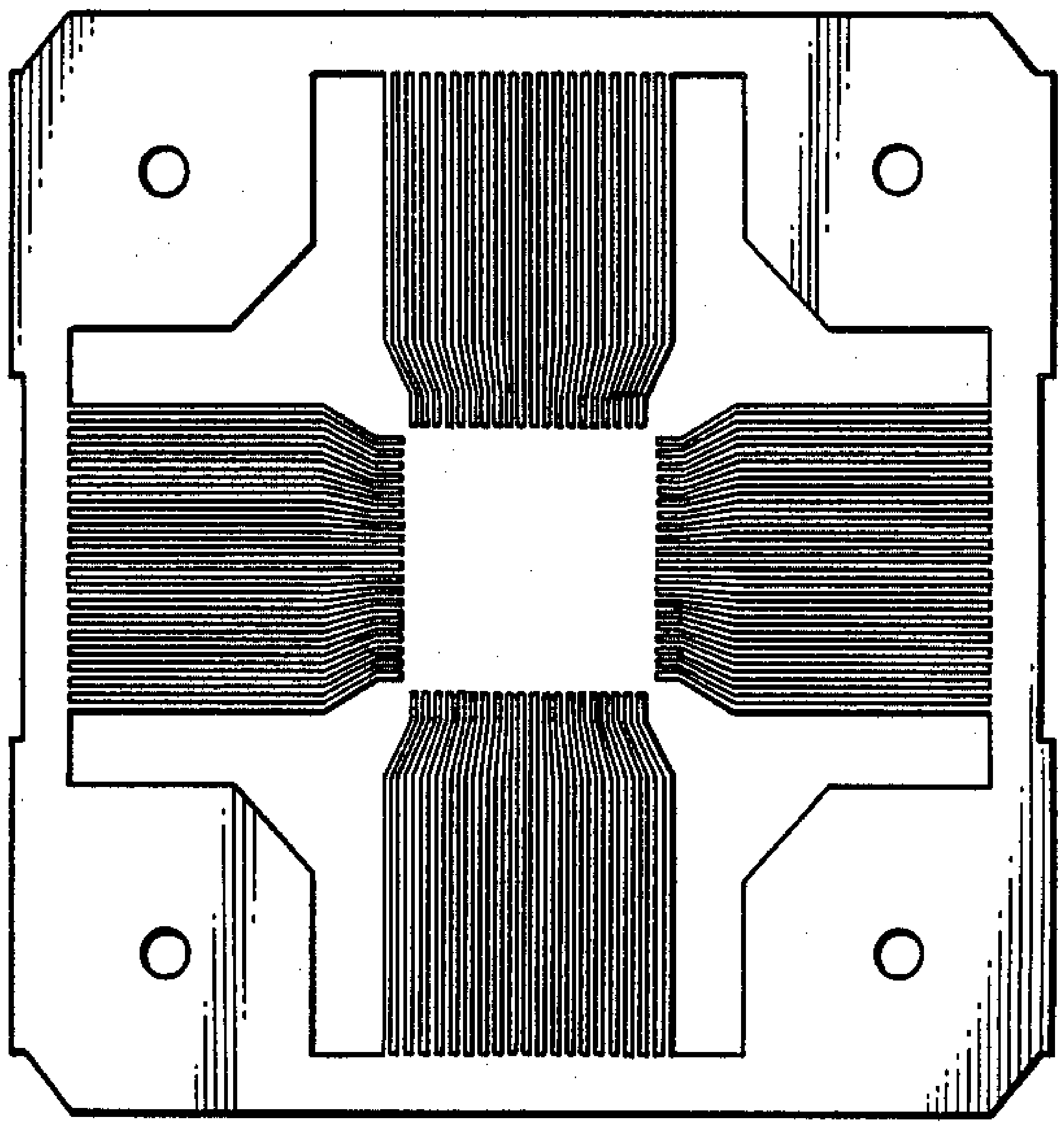

Fig. 1

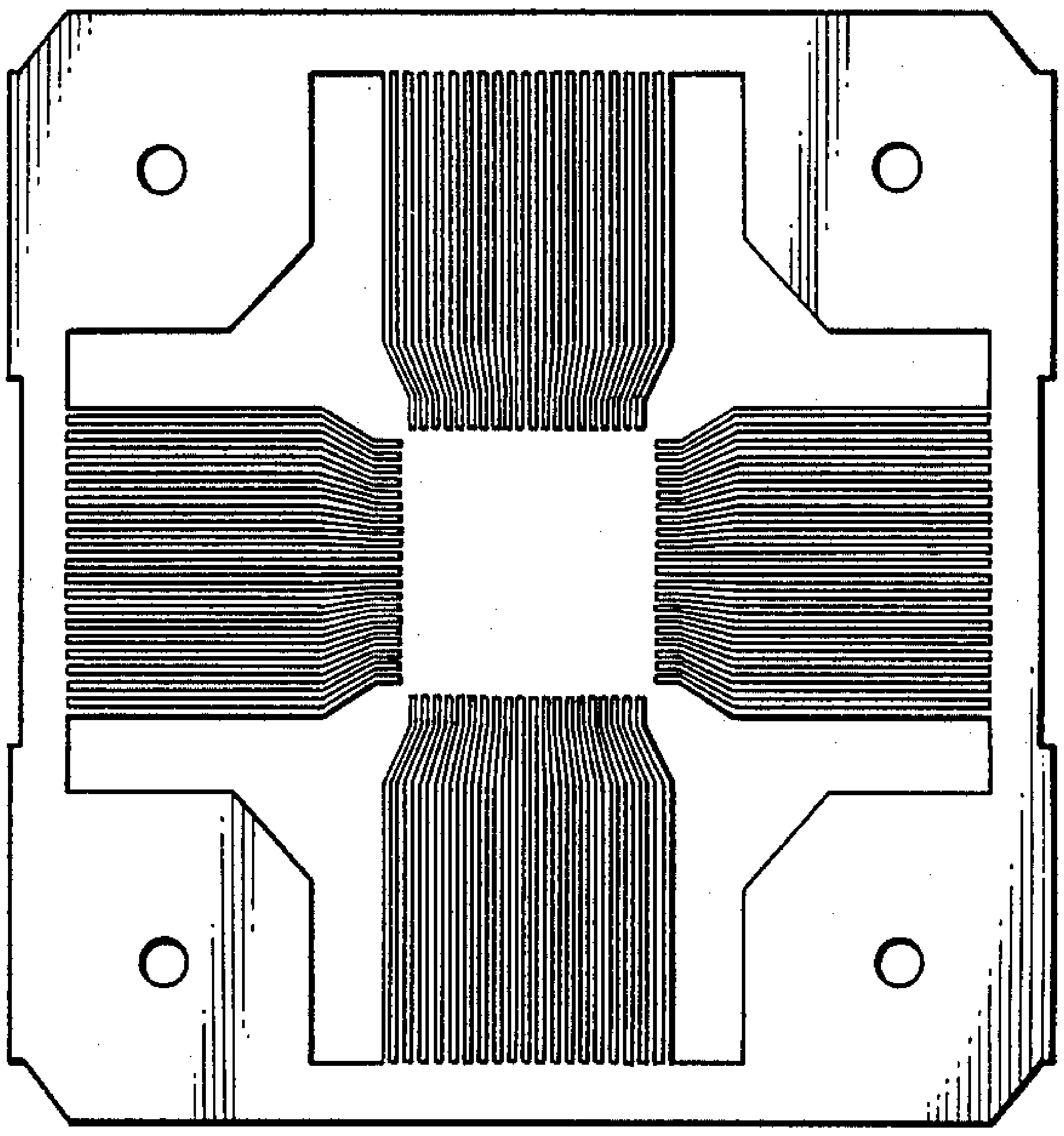

Fig. 2

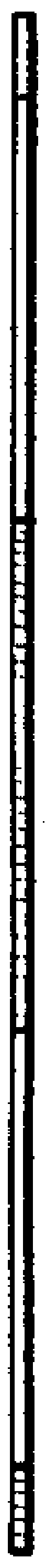

Fig. 3